RELIABILITY REPORT

FOR

MAX5418LETA+

PLASTIC ENCAPSULATED DEVICES

April 27, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Manager, Reliability Engineering

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Conclusion

The MAX5418LETA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX5417/MAX5418/MAX5419 nonvolatile, linear-taper, digital potentiometers perform the function of a mechanical potentiometer by replacing the mechanics with a simple 2-wire digital interface, allowing communication with multiple devices. Each device performs the same function as a discrete potentiometer or variable resistor and has 256 tap points. The devices feature an internal, nonvolatile EEPROM used to store the wiper position for initialization during power-up. The fast-mode I^2C-compatible serial interface allows communication at data rates up to 400kbps, minimizing board space and reducing interconnection complexity in many applications. Each device is available with one of four factory-preset addresses (see the *Selector Guide* in the full data sheet) and features an address input for a total of eight unique address combinations. The MAX5417/MAX5418/MAX5419 provide three nominal resistance values: 50k (MAX5417), 100k (MAX5418), or 200k (MAX5419). The nominal resistor temperature coefficient is 35ppm/°C end-to-end, and only 5ppm/°C ratiometric. This makes the devices ideal for applications requiring a low-temperature-coefficient variable resistor, such as low-drift, programmable gain-amplifier circuit configurations. The MAX5417/MAX5418/MAX5419 are available in a 3mm x 3mm 8-pin TDFN package, and are specified over the extended -40°C to +85°C temperature range.

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II. Manufacturing Information

A. Description/Function:	256-Tap, Nonvolatile, I²C-Interface, Digital Potentiometers
B. Process:	E35
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	China, Malaysia, Philippines, Thailand
F. Date of Initial Production:	March 12, 2004

III. Packaging Information

A. Package Type:	8-pin TDFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3154
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	54°C/W
K. Single Layer Theta Jc:	8.3°C/W
L. Multi Layer Theta Ja:	41°C/W
M. Multi Layer Theta Jc:	8.3°C/W

IV. Die Information

A. Dimensions:	61 X 45 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.35µm
F. Minimum Metal Spacing:	0.35µm
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

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V. Quality Assurance Information

A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 125°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 192 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 7.6 \times 10^{-9}$

λ = 7.6 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim"s reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the E35 Process results in a FIT Rate of 0.68 @ 25C and 11.68 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The DP16-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.

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Table 1
Reliability Evaluation Test Results

MAX5418LETA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 125°C Biased Time = 192 hrs.	DC Parameters & functionality	192	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

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